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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c620a-04-ss

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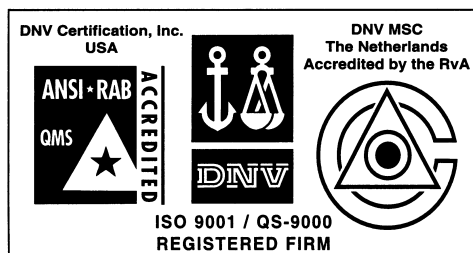
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PIC16C62X

TABLE 1-1: PIC16C62X FAMILY OF DEVICES

		PIC16C620 ⁽³⁾	PIC16C620A ⁽¹⁾⁽⁴⁾	PIC16CR620A ⁽²⁾	PIC16C621 ⁽³⁾	PIC16C621A ⁽¹⁾⁽⁴⁾	PIC16C622 ⁽³⁾	PIC16C622A ⁽¹⁾⁽⁴⁾
Clock	Maximum Frequency of Operation (MHz)	20	40	20	20	40	20	40
Memory	EPROM Program Memory (x14 words)	512	512	512	1K	1K	2K	2K
	Data Memory (bytes)	80	96	96	80	96	128	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMRO	TMR0	TMR0	TMR0	TMR0
	Comparators(s)	2	2	2	2	2	2	2
	Internal Reference Voltage	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Features	Interrupt Sources	4	4	4	4	4	4	4
	I/O Pins	13	13	13	13	13	13	13
	Voltage Range (Volts)	2.5-6.0	2.7-5.5	2.5-5.5	2.5-6.0	2.7-5.5	2.5-6.0	2.7-5.5
	Brown-out Reset	Yes	Yes	Yes	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC, 20-pin SSOP	18-pin DIP, SOIC, 20-pin SSOP	18-pin DIP, SOIC, 20-pin SSOP	18-pin DIP, SOIC, 20-pin SSOP	18-pin DIP, SOIC, 20-pin SSOP	18-pin DIP, SOIC, 20-pin SSOP	18-pin DIP, SOIC, 20-pin SSOP

All PICmicro[®] Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C62X Family devices use serial programming with clock pin RB6 and data pin RB7.

- Note 1:** If you change from this device to another device, please verify oscillator characteristics in your application.
- 2:** For ROM parts, operation from 2.0V - 2.5V will require the PIC16LCR62XA parts.
- 3:** For OTP parts, operation from 2.5V - 3.0V will require the PIC16LC62X part.
- 4:** For OTP parts, operation from 2.7V - 3.0V will require the PIC16LC62XA part.

PIC16C62X

3.1 Clocking Scheme/Instruction Cycle

The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2.

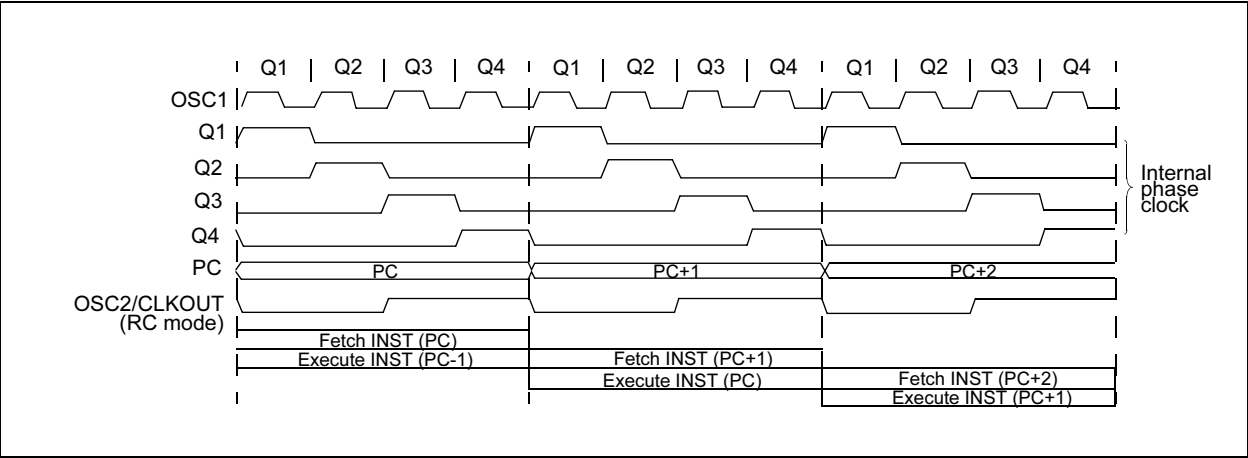
3.2 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., GOTO) then two cycles are required to complete the instruction (Example 3-1).

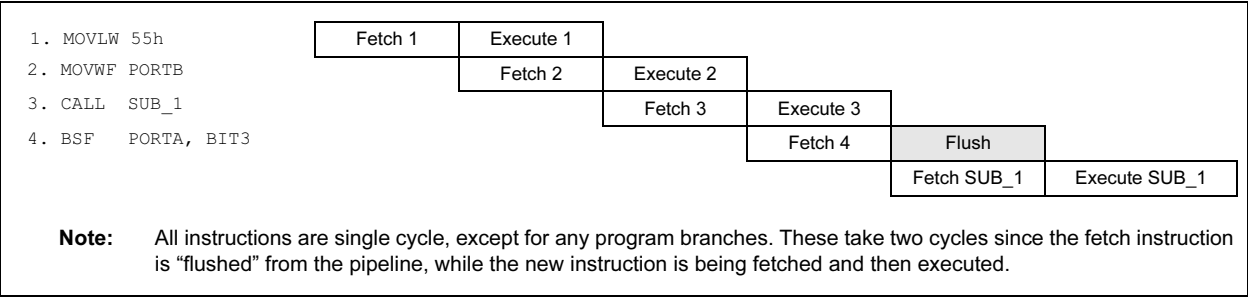
A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-2: CLOCK/INSTRUCTION CYCLE



EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



PIC16C62X

4.2.2.3 INTCON Register

The INTCON register is a readable and writable register, which contains the various enable and flag bits for all interrupt sources except the comparator module. See Section 4.2.2.4 and Section 4.2.2.5 for a description of the comparator enable and flag bits.

Note: Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>).

REGISTER 4-3: INTCON REGISTER (ADDRESS 0BH OR 8BH)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF
bit 7							bit 0

- bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all un-masked interrupts
0 = Disables all interrupts
- bit 6 **PEIE:** Peripheral Interrupt Enable bit
1 = Enables all un-masked peripheral interrupts
0 = Disables all peripheral interrupts
- bit 5 **TOIE:** TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 interrupt
0 = Disables the TMR0 interrupt
- bit 4 **INTE:** RB0/INT External Interrupt Enable bit
1 = Enables the RB0/INT external interrupt
0 = Disables the RB0/INT external interrupt
- bit 3 **RBIE:** RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt
- bit 2 **TOIF:** TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow
- bit 1 **INTF:** RB0/INT External Interrupt Flag bit
1 = The RB0/INT external interrupt occurred (must be cleared in software)
0 = The RB0/INT external interrupt did not occur
- bit 0 **RBIF:** RB Port Change Interrupt Flag bit
1 = When at least one of the RB<7:4> pins changed state (must be cleared in software)
0 = None of the RB<7:4> pins have changed state

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

TABLE 5-3: PORTB FUNCTIONS

Name	Bit #	Buffer Type	Function
RB0/INT	bit0	TTL/ST ⁽¹⁾	Input/output or external interrupt input. Internal software programmable weak pull-up.
RB1	bit1	TTL	Input/output pin. Internal software programmable weak pull-up.
RB2	bit2	TTL	Input/output pin. Internal software programmable weak pull-up.
RB3	bit3	TTL	Input/output pin. Internal software programmable weak pull-up.
RB4	bit4	TTL	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up.
RB5	bit5	TTL	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up.
RB6	bit6	TTL/ST ⁽²⁾	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up. Serial programming clock pin.
RB7	bit7	TTL/ST ⁽²⁾	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up. Serial programming data pin.

Legend: ST = Schmitt Trigger, TTL = TTL input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

TABLE 5-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
81h	OPTION	RBP $\overline{\text{U}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: u = unchanged, x = unknown

Note 1: Shaded bits are not used by PORTB.

6.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed “on-the-fly” during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 6-1) must be executed when changing the prescaler assignment from Timer0 to WDT.)

EXAMPLE 6-1: CHANGING PRESCALER (TIMER0→WDT)

```

1.BCF      STATUS, RP0    ;Skip if already in
                           ;Bank 0
2.CLRWDT                      ;Clear WDT
3.CLRF      TMR0          ;Clear TMR0 & Prescaler
4.BSF      STATUS, RP0    ;Bank 1
5.MOVLW     '00101111'b;  ;These 3 lines (5, 6, 7)
6.MOVWF     OPTION        ;are required only if
                           ;desired PS<2:0> are
7.CLRWDT                      ;000 or 001
8.MOVLW     '00101xxx'b   ;Set Postscaler to
9.MOVWF     OPTION        ;desired WDT rate
10.BCF      STATUS, RP0    ;Return to Bank 0
    
```

To change prescaler from the WDT to the TMR0 module, use the sequence shown in Example 6-2. This precaution must be taken even if the WDT is disabled.

EXAMPLE 6-2: CHANGING PRESCALER (WDT→TIMER0)

```

CLRWDT                      ;Clear WDT and
                           ;prescaler
BSF      STATUS, RP0
MOVLW     b'xxxx0xxx'      ;Select TMR0, new
                           ;prescale value and
                           ;clock source
MOVWF     OPTION_REG
BCF      STATUS, RP0
    
```

TABLE 6-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
01h	TMR0	Timer0 module register								xxxx xxxx	uuuu uuuu
0Bh/8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: — = Unimplemented locations, read as '0', u = unchanged, x = unknown

Note: Shaded bits are not used by TMR0 module.

PIC16C62X

NOTES:

9.3 RESET

The PIC16C62X differentiates between various kinds of RESET:

- Power-on Reset (POR)
- $\overline{\text{MCLR}}$ Reset during normal operation
- $\overline{\text{MCLR}}$ Reset during SLEEP
- WDT Reset (normal operation)
- WDT wake-up (SLEEP)
- Brown-out Reset (BOR)

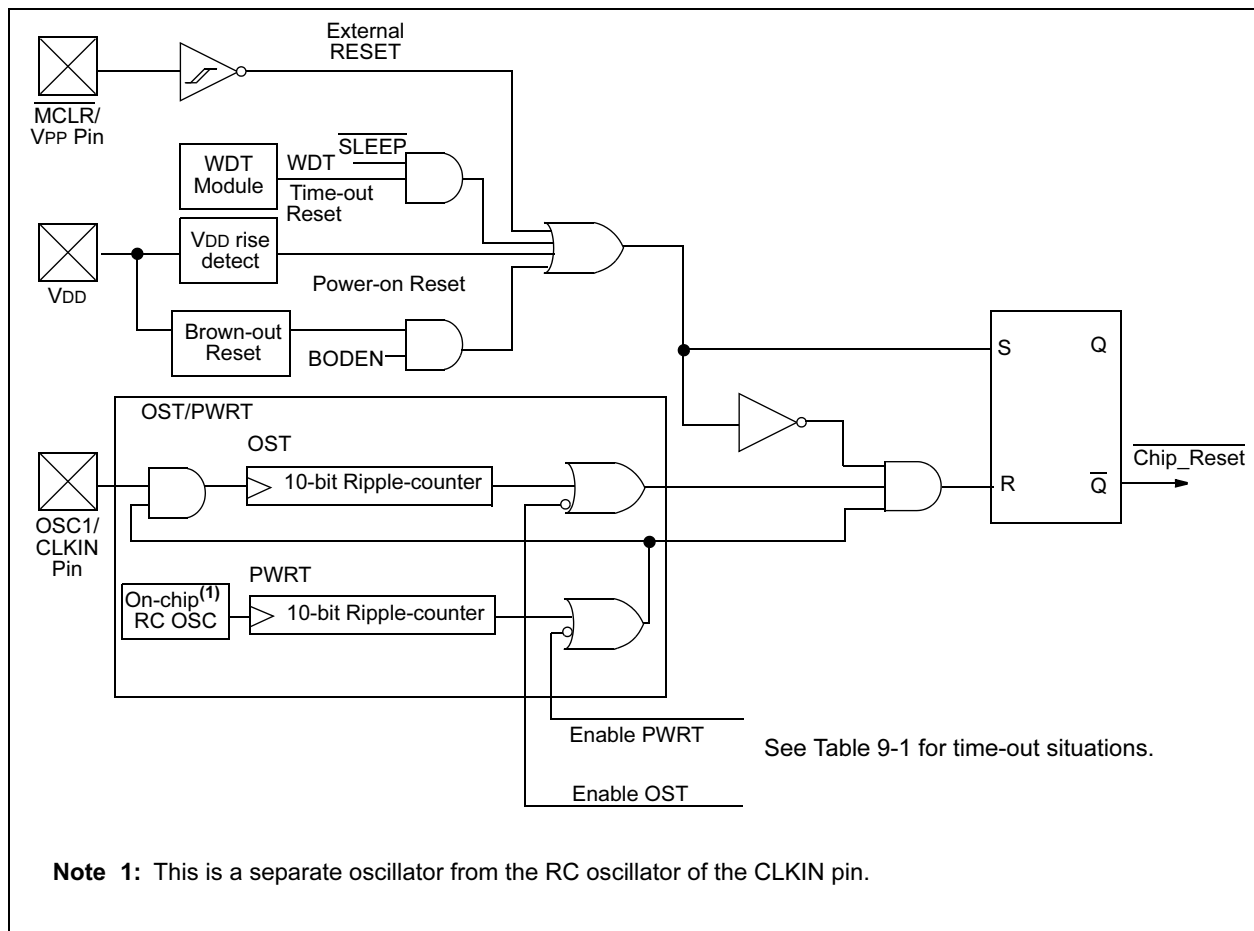
Some registers are not affected in any RESET condition. Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on Power-on Reset,

$\overline{\text{MCLR}}$ Reset, WDT Reset and $\overline{\text{MCLR}}$ Reset during SLEEP. They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different RESET situations as indicated in Table 9-2. These bits are used in software to determine the nature of the RESET. See Table 9-5 for a full description of RESET states of all registers.

A simplified block diagram of the on-chip RESET circuit is shown in Figure 9-6.

The $\overline{\text{MCLR}}$ Reset path has a noise filter to detect and ignore small pulses. See Table 12-5 for pulse width specification.

FIGURE 9-6: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



9.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the PD bit in the STATUS register is cleared, the TO bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before SLEEP was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at VDD or VSS with no external circuitry drawing current from the I/O pin and the comparators and VREF should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at VDD or VSS for lowest current consumption. The contribution from on chip pull-ups on PORTB should be considered.

The MCLR pin must be at a logic high level (VIHMC).

Note: It should be noted that a RESET generated by a WDT time-out does not drive MCLR pin low.

The first event will cause a device RESET. The two latter events are considered a continuation of program execution. The \overline{TO} and \overline{PD} bits in the STATUS register can be used to determine the cause of device RESET. PD bit, which is set on power-up, is cleared when SLEEP is invoked. \overline{TO} bit is cleared if WDT wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

Note: If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from SLEEP. The SLEEP instruction is completely executed.

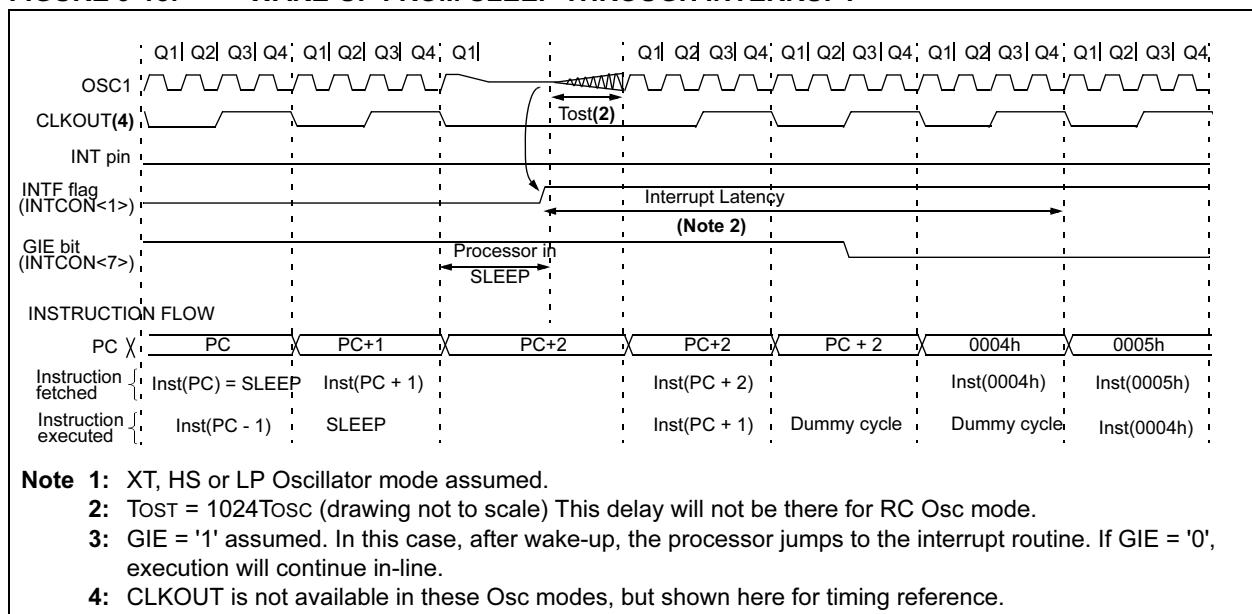
9.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External RESET input on MCLR pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

The WDT is cleared when the device wakes up from SLEEP, regardless of the source of wake-up.

FIGURE 9-18: WAKE-UP FROM SLEEP THROUGH INTERRUPT



SWAPF		Swap Nibbles in f							
Syntax:	[<i>label</i>] SWAPF f,d								
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$								
Operation:	$(f<3:0>) \rightarrow (dest<7:4>),$ $(f<7:4>) \rightarrow (dest<3:0>)$								
Status Affected:	None								
Encoding:	<table border="1"><tr><td>00</td><td>1110</td><td>dfff</td><td>ffff</td></tr></table>					00	1110	dfff	ffff
00	1110	dfff	ffff						
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.								
Words:	1								
Cycles:	1								
Example	SWAPF REG, 0								
	Before Instruction								
	REG1 = 0xA5								
	After Instruction								
	REG1 = 0xA5								
	W = 0x5A								

TRIS	Load TRIS Register				
Syntax:	[<i>label</i>] TRIS f				
Operands:	$5 \leq f \leq 7$				
Operation:	(W) → TRIS register f;				
Status Affected:	None				
Encoding:	<table><tr><td>00</td><td>0000</td><td>0110</td><td>0fff</td></tr></table>	00	0000	0110	0fff
00	0000	0110	0fff		
Description:	The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.				
Words:	1				
Cycles:	1				
Example	<table><tr><td>To maintain upward compatibility with future PICmicro[®] products, do not use this instruction.</td></tr></table>	To maintain upward compatibility with future PICmicro[®] products, do not use this instruction.			
To maintain upward compatibility with future PICmicro[®] products, do not use this instruction.					

XORLW		Exclusive OR Literal with W			
Syntax:	[<i>label</i> XORLW k 				

XORWF

Exclusive OR W with f

Syntax:

[*label*] XORWF f,d

Operands:

$0 \leq f \leq 127$
 $d \in [0,1]$

Operation:

(W) .XOR. (f) → (dest)

Status Affected:

Z

Encoding:

00	0110	dfff	ffff
----	------	------	------

Description:

Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

Words:

1

Cycles:

1

Example

XORWF REG 1

Before Instruction

REG = 0xAF

W = 0xB5

After Instruction

REG = 0x1A

W = 0xB5

FIGURE 12-3: PIC16C62XA VOLTAGE-FREQUENCY GRAPH, $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$

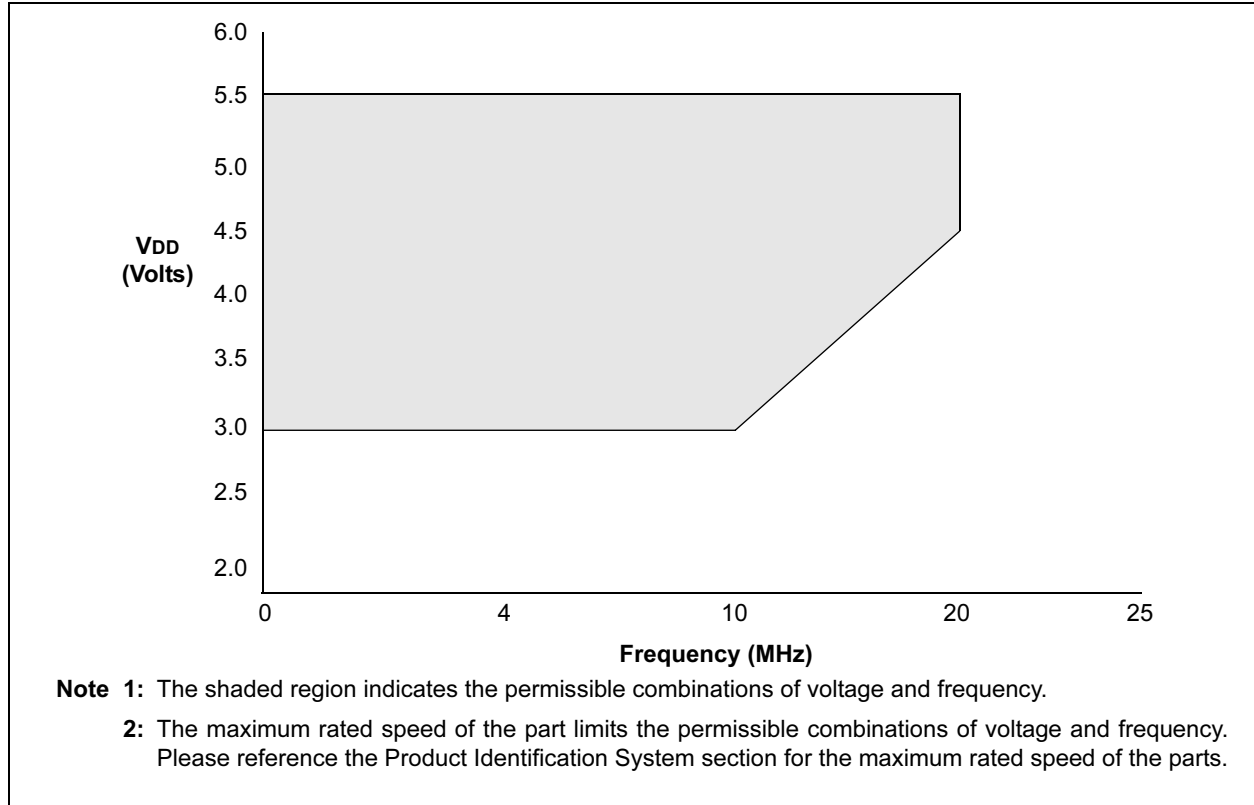
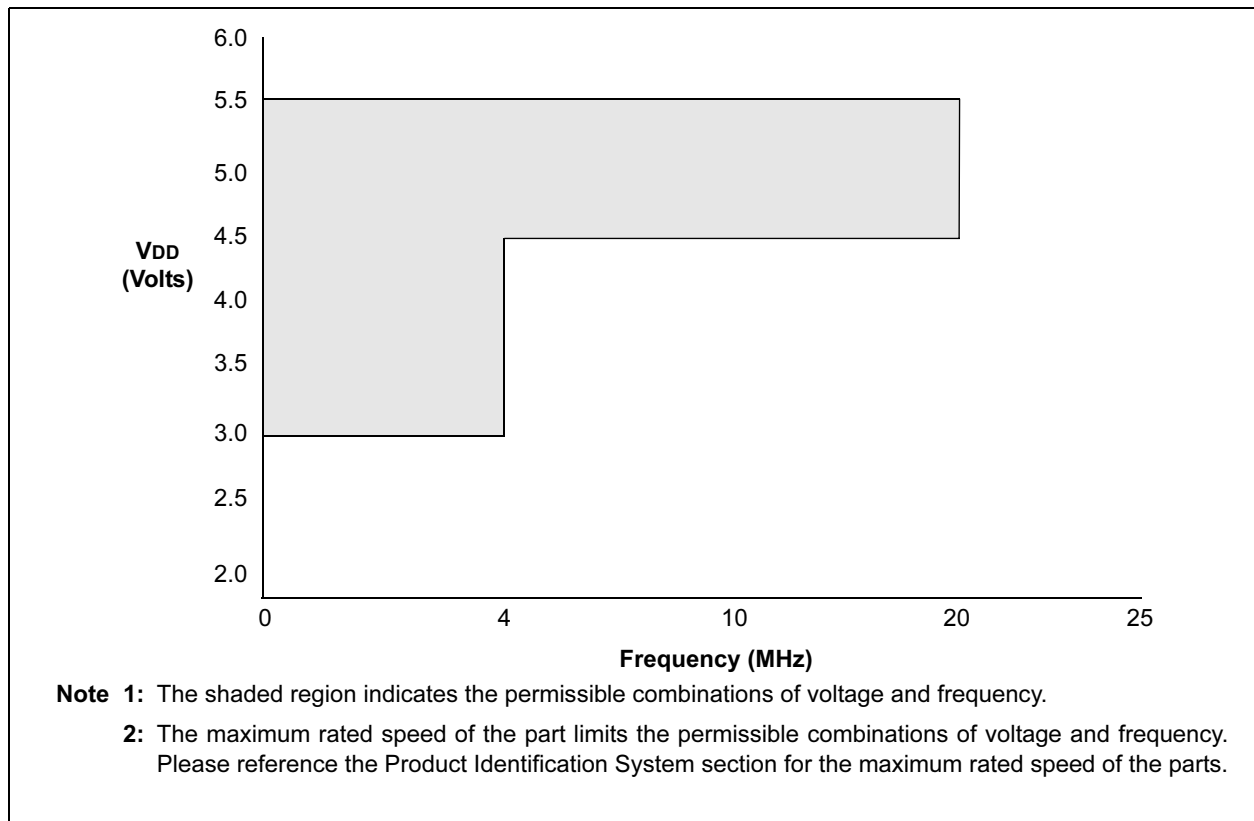
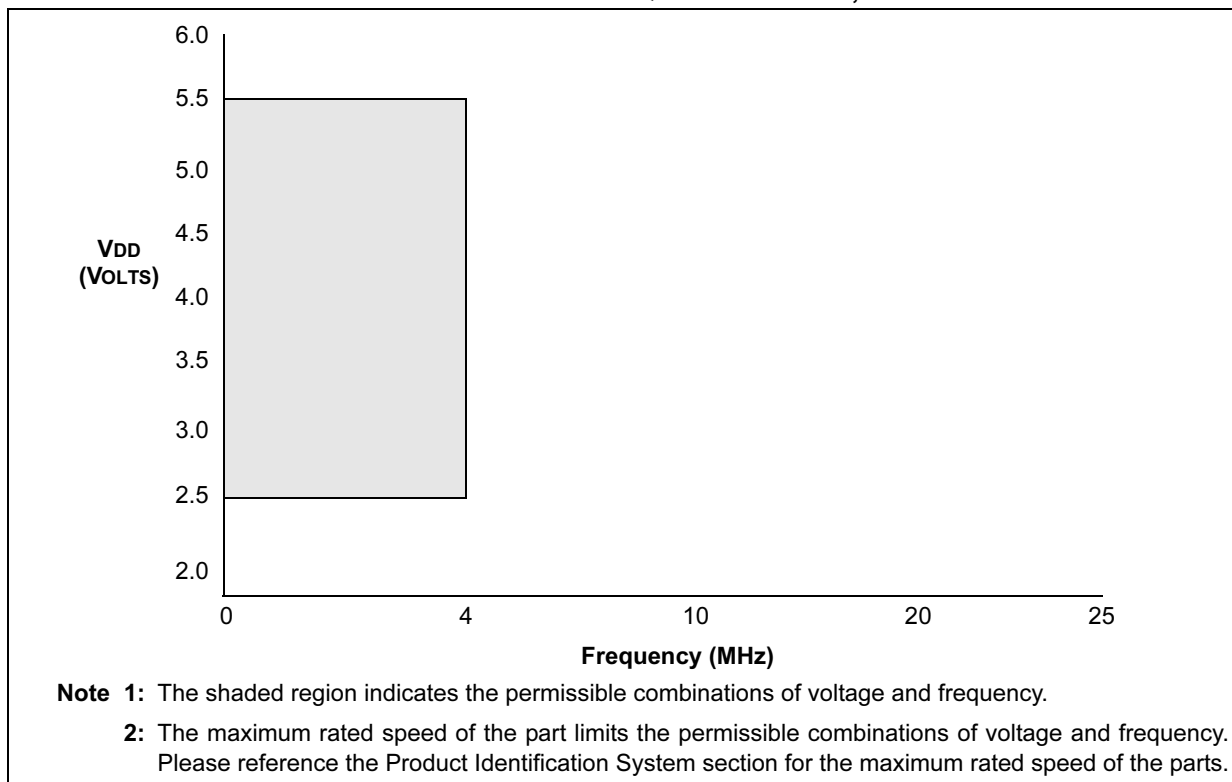


FIGURE 12-4: PIC16C62XA VOLTAGE-FREQUENCY GRAPH, $-40^{\circ}\text{C} \leq T_A \leq 0^{\circ}\text{C}$, $+70^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$



PIC16C62X

FIGURE 12-9: PIC16LCR62XA VOLTAGE-FREQUENCY GRAPH, $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$



PIC16C62X

12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended) PIC16C62XA-20 (Commercial, Industrial, Extended) PIC16LC62XA-04 (Commercial, Industrial, Extended (CONT.))

PIC16C62XA			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LC62XA			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D022	ΔI _{WDT}	WDT Current ⁽⁵⁾	—	6.0	10	μA	V _{DD} = 4.0V (125°C)
D022A	ΔI _{BOR}	Brown-out Reset Current ⁽⁵⁾	—	75	125	μA	BOD enabled, V _{DD} = 5.0V
D023	ΔI _{COMP}	Comparator Current for each Comparator ⁽⁵⁾	—	30	60	μA	V _{DD} = 4.0V
D023A	ΔI _{VREF}	VREF Current ⁽⁵⁾	—	80	135	μA	V _{DD} = 4.0V
D022	ΔI _{WDT}	WDT Current ⁽⁵⁾	—	6.0	10	μA	V _{DD} =4.0V (125°C)
D022A	ΔI _{BOR}	Brown-out Reset Current ⁽⁵⁾	—	75	125	μA	BOD enabled, V _{DD} = 5.0V
D023	ΔI _{COMP}	Comparator Current for each Comparator ⁽⁵⁾	—	30	60	μA	V _{DD} = 4.0V
D023A	ΔI _{VREF}	VREF Current ⁽⁵⁾	—	80	135	μA	V _{DD} = 4.0V
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which V_{DD} can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all I_{DD} measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to V_{DD},

MCLR = V_{DD}; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to V_{DD} or V_{SS}.

4: For RC osc configuration, current through R_{EXT} is not included. The current through the resistor can be estimated by the formula: I_r = V_{DD}/2R_{EXT} (mA) with R_{EXT} in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base I_{DD} or I_{PD} measurement.

6: Commercial temperature range only.

12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended) PIC16CR62XA-20 (Commercial, Industrial, Extended) PIC16LCR62XA-04 (Commercial, Industrial, Extended)

PIC16CR62XA-04 PIC16CR62XA-20			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LCR62XA-04			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-7, 12-8, 12-9
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-7, 12-8, 12-9
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current ⁽²⁾	—	1.2	1.7	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	500	900	μA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, (Note 4)
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, (Note 6)
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode
			—	3.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode
			—	35	70	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current ⁽²⁾	—	1.2	1.7	mA	FOSC = 4.0 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	400	800	μA	FOSC = 4.0 MHz, VDD = 2.5V, WDT disabled, XT mode (Note 4)
			—	35	70	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended) (CONT.)

PIC16C62X/C62XA/CR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LC62X/LC62XA/LCR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D040	V _{IH}	Input High Voltage I/O ports with TTL buffer	2.0V 0.25 V _{DD} + 0.8V	—	V _{DD} V _{DD}	V	V _{DD} = 4.5V to 5.5V otherwise (Note 1)
D041		with Schmitt Trigger input	0.8 V _{DD}	—	V _{DD}		
D042		MCLR RA4/T0CKI	0.8 V _{DD}	—	V _{DD}	V	
D043 D043A		OSC1 (XT, HS and LP) OSC1 (in RC mode)	0.7 V _{DD} 0.9 V _{DD}	—	V _{DD}	V	
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	V _{DD} = 5.0V, V _{PIN} = V _{SS}
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	V _{DD} = 5.0V, V _{PIN} = V _{SS}
D060	I _{IL}	Input Leakage Current ^(2, 3) I/O ports (Except PORTA)			±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D061		PORTA	—	—	±0.5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
D063		OSC1, MCLR	—	—	±5.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP osc configuration
D060	I _{IL}	Input Leakage Current ^(2, 3) I/O ports (Except PORTA)			±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D061		PORTA	—	—	±0.5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
D063		OSC1, MCLR	—	—	±5.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP osc configuration
D080	V _{OL}	Output Low Voltage I/O ports	—	—	0.6	V	I _{OL} = 8.5 mA, V _{DD} = 4.5V, -40° to $+85^{\circ}\text{C}$
			—	—	0.6	V	I _{OL} = 7.0 mA, V _{DD} = 4.5V, $+125^{\circ}\text{C}$
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	I _{OL} = 1.6 mA, V _{DD} = 4.5V, -40° to $+85^{\circ}\text{C}$
			—	—	0.6	V	I _{OL} = 1.2 mA, V _{DD} = 4.5V, $+125^{\circ}\text{C}$

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

13.0 DEVICE CHARACTERIZATION INFORMATION

The graphs and tables provided in this section are for design guidance and are not tested. In some graphs or tables, the data presented is outside specified operating range (e.g., outside specified VDD range). This is for information only and devices will operate properly only within the specified range.

The data presented in this section is a statistical summary of data collected on units from different lots over a period of time. "Typical" represents the mean of the distribution, while "max" or "min" represents (mean + 3 σ) and (mean - 3 σ) respectively, where σ is standard deviation.

FIGURE 13-1: I_{DD} VS. FREQUENCY (XT MODE, V_{DD} = 5.5V)

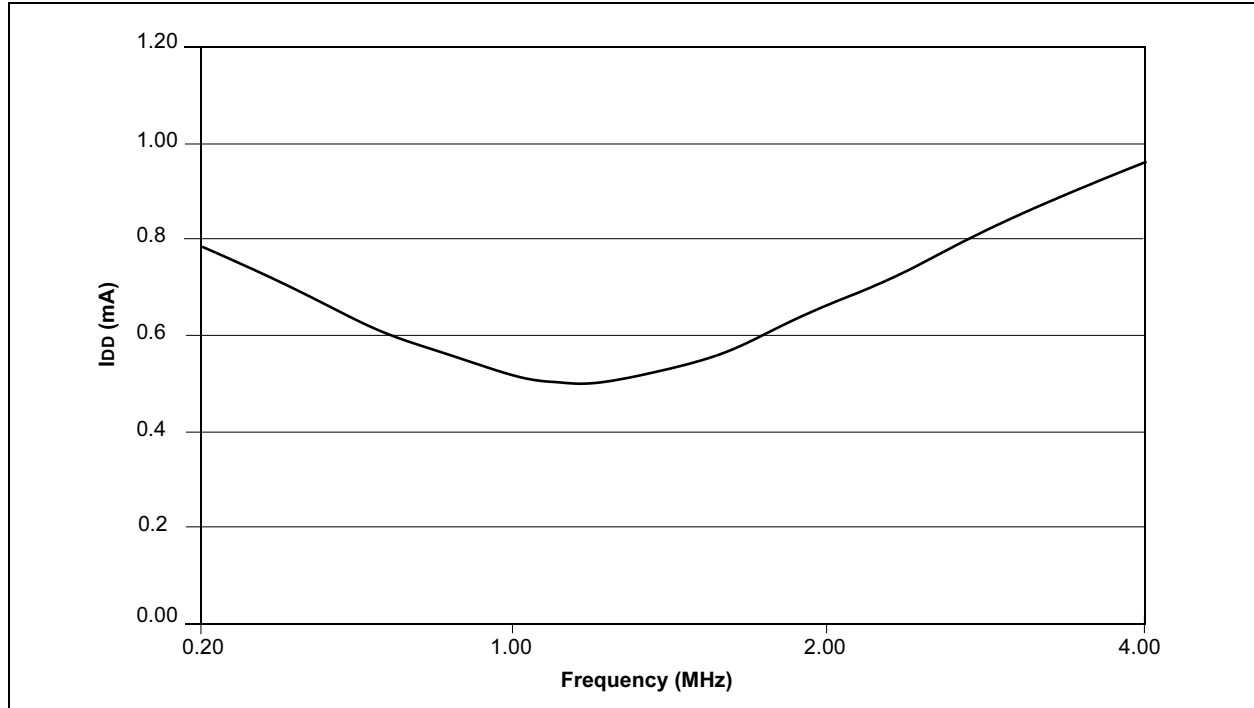


FIGURE 13-2: PIC16C622A I_{PD} VS. V_{DD} (WDT DISABLE)

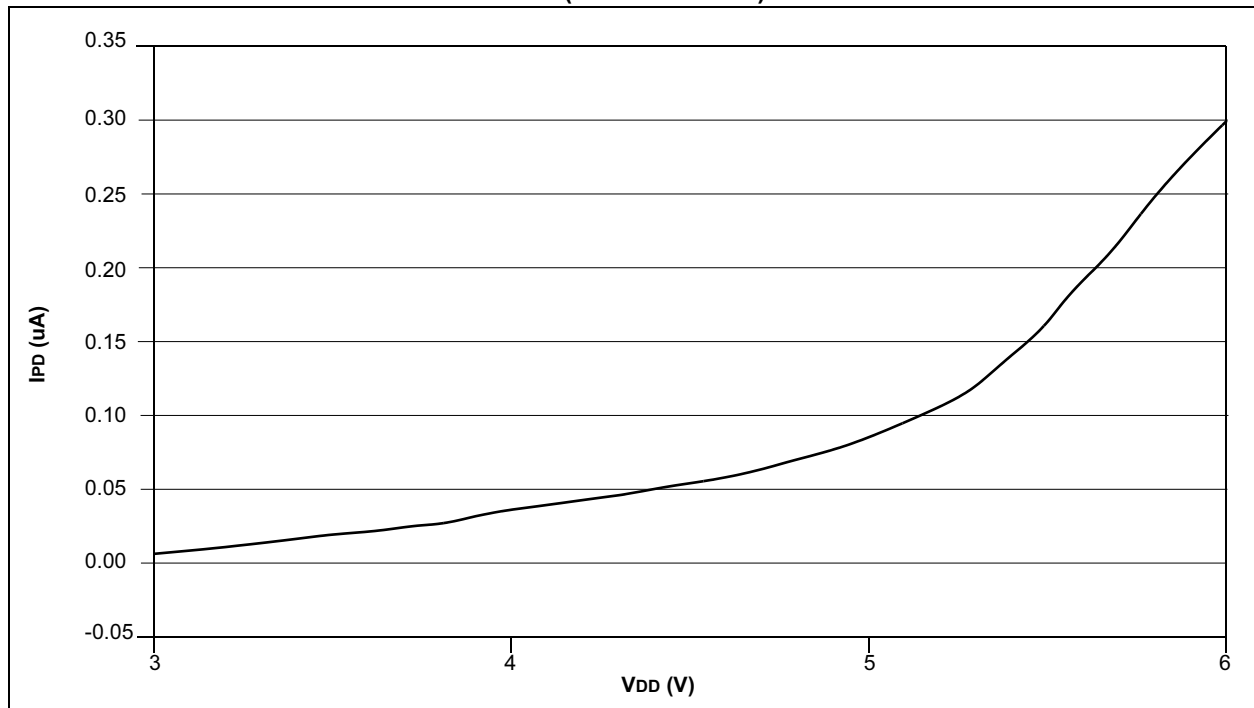


FIGURE 13-5: I_{OH} vs. V_{OH} , $V_{DD} = 3.0V$

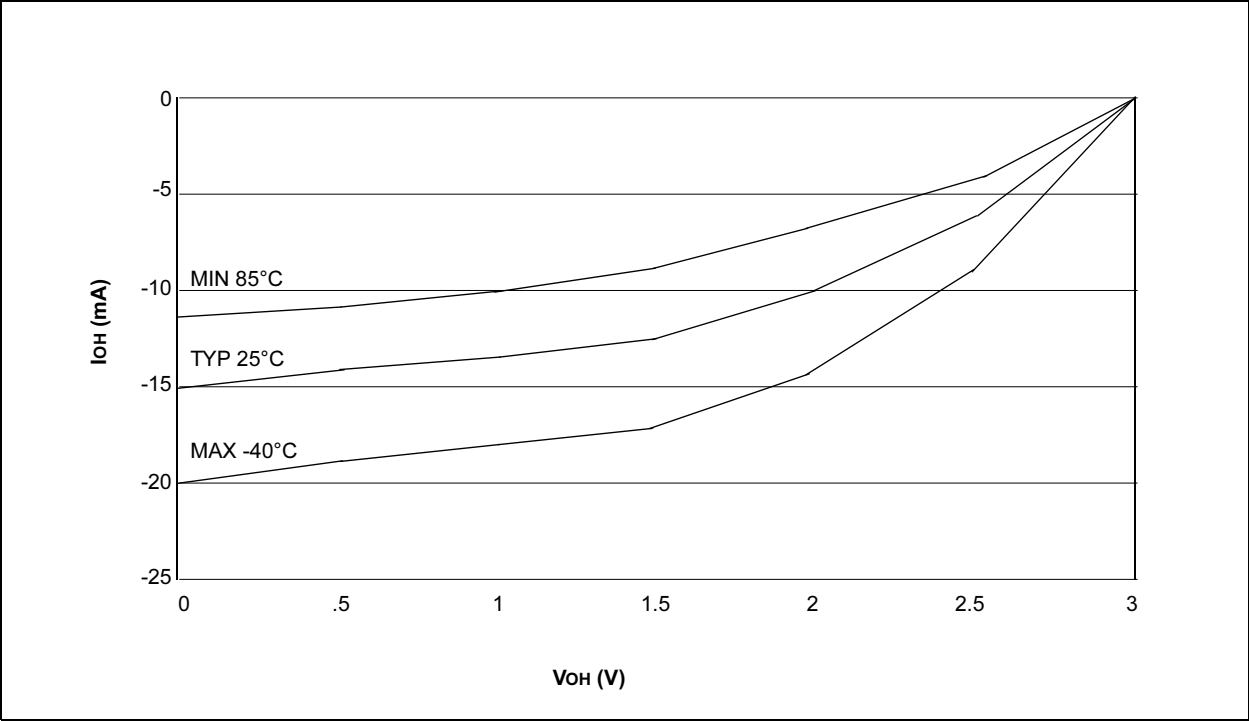
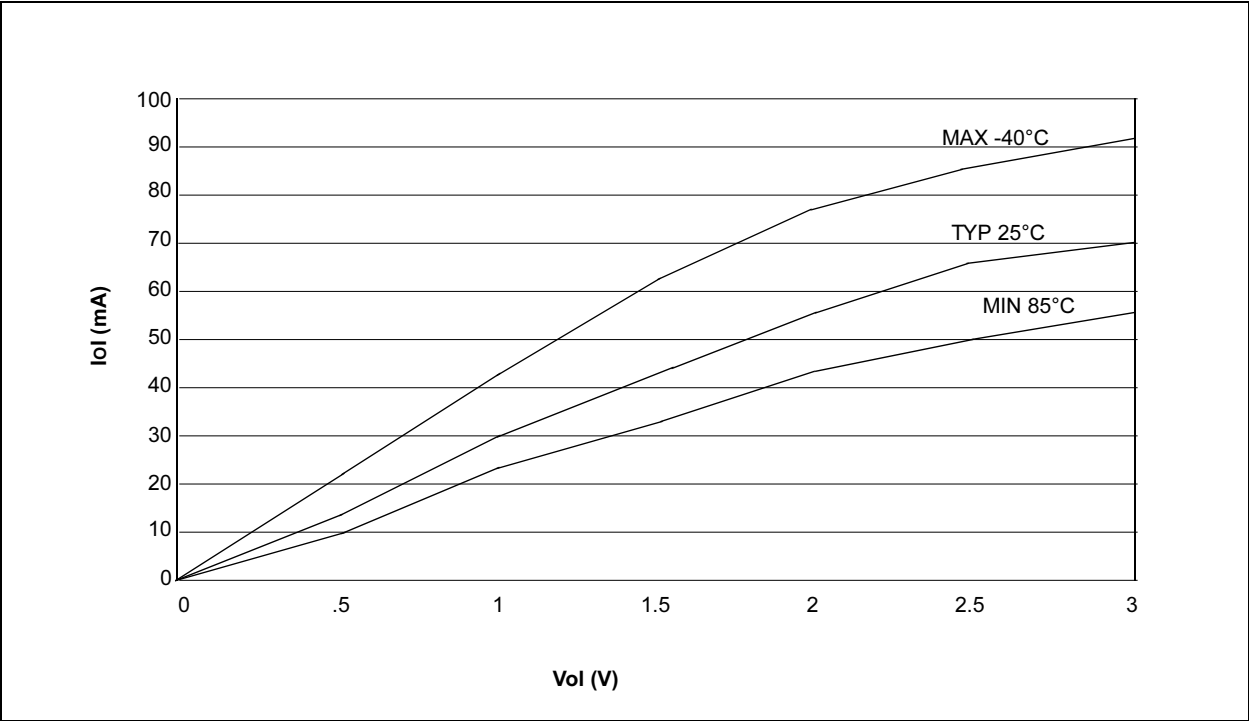
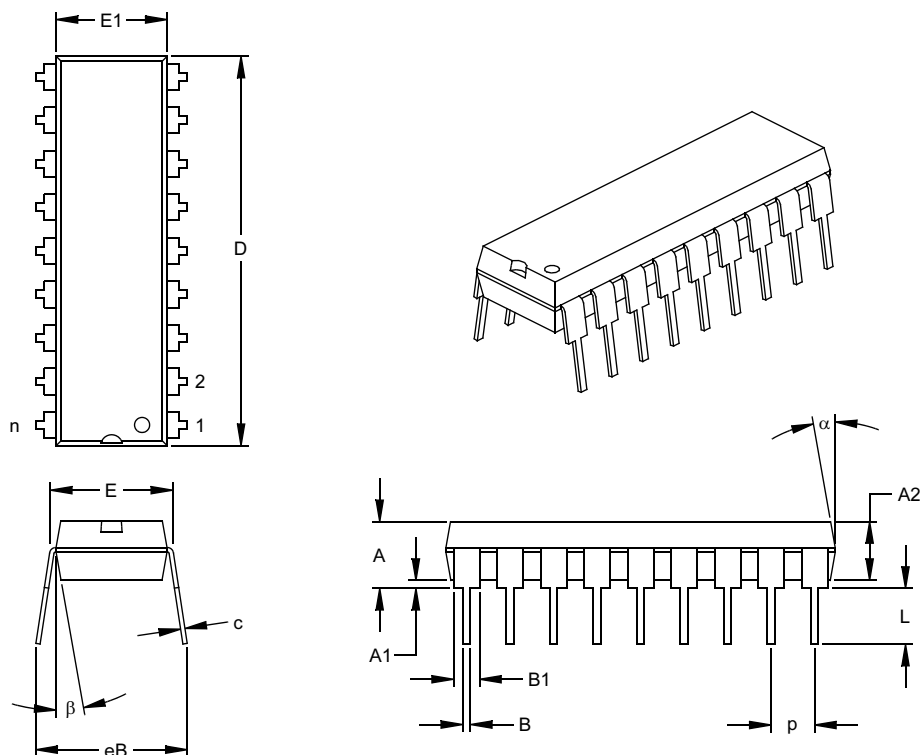


FIGURE 13-6: I_{OL} vs. V_{OL} , $V_{DD} = 5.5V$



PIC16C62X

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter

§ Significant Characteristic

Notes:

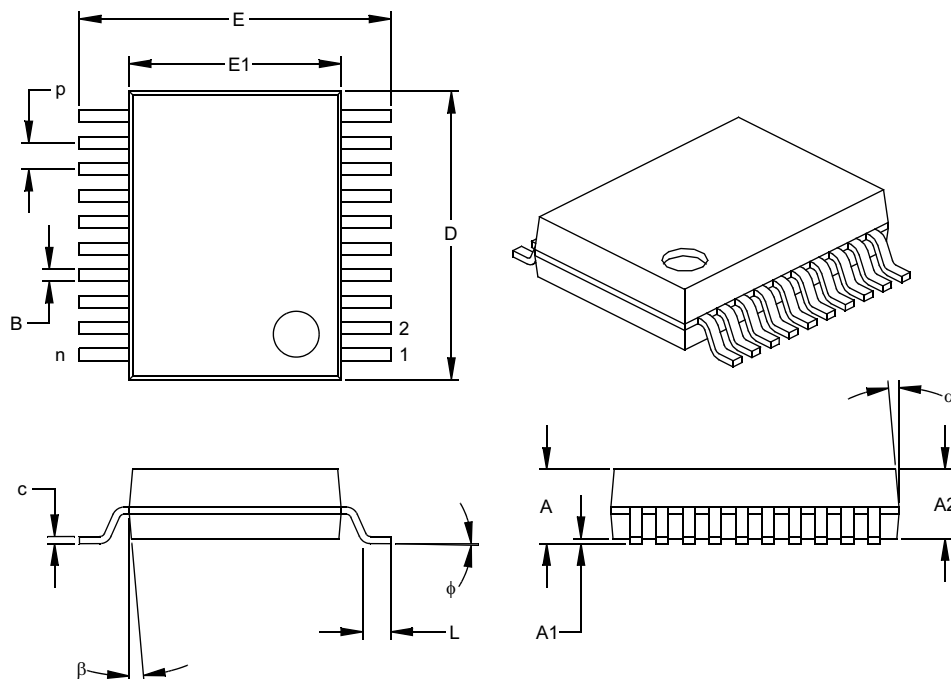
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-007

PIC16C62X

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-150

Drawing No. C04-072



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